

C1206C223G2TACTU

Aliases (C1206C223G2TAC7800)

SMD Comm X8G HT150C, Ceramic, 0.022 uF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	36 mg
Shelf Life	78 Weeks
MSL	1

0.022 uF

Time is 1000 Hours

45.4545 GOhms

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	1.6mm +/-0.20mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

	3.2mm +/-0.2mm	Measurement Condition	1 kHz 1.0Vrms
	1.6mm +/-0.2mm	Tolerance	2%
	1.6mm +/-0.20mm	Voltage DC	200 VDC
	1.5mm MIN	Dielectric Withstanding Voltage	500 VDC
	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
ifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
tity	2000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee

Insulation Resistance

Specifications

Capacitance

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2000

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